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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chuen Rong Leu et al.

Assignee: Bridge Semiconductor Corporation

Title: METHOD OF MAKING A SEMICONDUCTOR CHIP
ASSEMBLY WITH AN EMBEDDED METAL PILLAR

Patent No.: 7,094,676 Issued: August 22, 2006

Serial No.: 10/719,823 Filed: November 21, 2003

Examiner: Dang, P. Group Art Unit: 2818

Atty. Docket No.: BDG024-1

COMMISSIONER FOR PATENTS

P.O. Box 1450

Alexandria, VA 22313-1450

Attention: Decision and Certificate of Correction
Branch of the Patent Issue Division

**REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT
FOR PTO MISTAKE**

Applicant hereby requests a Certificate of Correction for the captioned-patent due to a mistake by the Patent and Trademark Office in accordance with 37 C.F.R. § 1.322(a).

Title

The Transmittal filed on November 21, 2003 listed the Title as "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR."

The Preliminary Amendment filed on November 21, 2003 changed the Title to "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR."

Certificate
SEP 05 2006
of Correction

SEP 05 2006

The Request for Corrected Filing Receipt filed on April 26, 2006 corrected the Title as follows:

The Title should be "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR" (rather than "SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR") as set forth in the Transmittal and the Preliminary Amendment.

The Issue Fee Transmittal filed on May 5, 2006 corrected the Title to "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR."

The Corrected Filing Receipt mailed on May 10, 2006 listed the Title as "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR."

However, the in captioned-patent, the Title is "SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR". Therefore, in the captioned-patent, the Title should be "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR."

Claims 121, 141, 161 and 181

Claims 221, 241, 261 and 281 were presented in the Preliminary Amendment filed on November 21, 2003. Claims 221, 241, 261 and 281 as presented in the Preliminary Amendment recite the following two subparagraphs at lines 3-5:

providing a metal base with first and second opposing surfaces;

forming an etch mask on the first surface of the metal base and a routing line on the second surface of the metal base;

Claims 221, 241, 261 and 281 were amended in the Second Preliminary Amendment filed on May 24, 2004 as follows:

providing a metal base, an etch mask and a routing line,
wherein the metal base includes ~~with~~ first and second opposing surfaces, the;

~~— forming an etch mask is formed on the first surface of the metal base and the a routing line is formed on the second surface of the metal base;~~

Claims 221, 241, 261 and 281 were therefore amended in the Second Preliminary Amendment to combine the two subparagraphs at lines 3-5 into a single subparagraph (and thus combine the two steps at lines 3-5 into a single step) as follows:

providing a metal base, an etch mask and a routing line,
wherein the metal base includes first and second opposing surfaces,
the etch mask is formed on the first surface of the metal base and
the routing line is formed on the second surface of the metal base;

In the captioned-patent, claims 221, 241, 261 and 281 were renumbered as claims 121, 141, 161 and 181, respectively. However, in the captioned-patent, claims 121, 141, 161 and 181 recite the following two subparagraphs at lines 3-8:

providing a metal base, an etch mask and a routing line,
wherein the metal base includes first and second opposing surfaces,
the;

etch mask is formed on the first surface of the metal base
and the routing line is formed on the second surface of the metal base;

Therefore, in the captioned-patent, in claims 121, 141, 161 and 181, the two subparagraphs at lines 3-8 should be a single subparagraph and “;” should be deleted after “the” at line 5.

More particularly, the two subparagraphs “providing a metal base . . . of the metal base;” at column 53, lines 31-36 should be a single subparagraph and “;” should be deleted after “the” at

column 53, line 33 (claim 121), the two subparagraphs “providing a metal base . . . of the metal base;” at column 55, lines 46-51 should be a single subparagraph and “;” should be deleted after “the” at column 55, line 48 (claim 141), the two subparagraphs “providing a metal base . . . of the metal base;” at column 57, lines 56-61 should be a single subparagraph and “;” should be deleted after “the” at column 57, line 58 (claim 161) and the two subparagraphs “providing a metal base . . . of the metal base;” at column 60, lines 15-20 should be a single subparagraph and “;” should be deleted after “the” at column 60, line 17 (claim 181).

Claim 294

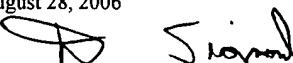
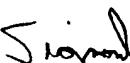
Claim 394 was presented in the Preliminary Amendment. Claim 394 recites “claim 393” at line 1 (page 59). In the captioned-patent, claims 393 and 394 were renumbered as claims 293 and 294, respectively. However, in the captioned-patent, claim 294 recites “claim 291” at column 71, line 16. Therefore, in the captioned-patent, “291” should be changed to -- 293 -- at column 71, line 16 (claim 294).

Certificate

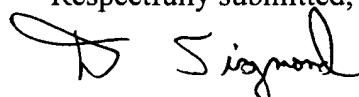
A PTO/SB/44 (also Form PTO-1050) which is suitable for printing is attached.

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David M. Sigmond
487 Blackfoot Street
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David M. Sigmond Attorney for Applicant	8/28/06 Date of Signature

Respectfully submitted,



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SEP 05 2006

(Also Form PTO-1050)

UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO.: 7,094,676 B1
DATED: August 22, 2006
INVENTOR: Chuen-Rong Leu et al.

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

The Title is "METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR".

Column 53

Lines 31-36, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 33, delete ";" after "the".

Column 55

Lines 46-51, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 48, delete ";" after "the".

Column 57

Lines 56-61, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 58, delete ";" after "the".

Column 60

Lines 15-20, "providing a metal base . . . of the metal base;" is a subparagraph.
Line 17, delete ";" after "the".

Column 71

Line 16, change "291" to -- 293 --.

MAILING ADDRESS OF SENDER:

PATENT NO. 7,094,676

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